

Manufacturing Capabilities

		Standard	Extended Capability (Limited Qty)
Material Type	2 Layers	FR-4, FR-4(TG-170°C)	Arlon*, Duroid*, Rogers*, Polymide*, Kapton, metal clad & others
	4 Layers & Above	FR-4, FR-4 (TG-170°C)	Arlon*, Duroid*, Rogers400X* (FR-4 B-Stage), metal clad
Material Thickness	2 Layers	.010" - .093"	.008" - .125"
	4 Layers	.031" - .093"	.021" - .125"
	6 Layers	.063" - .093"	.031" - .125"
	8-10 Layers	.062" - .093"	.050" - .125"
Layer Count		1 -10	12 -16
	2 Layers	16.50" x 22.50" (max)	16.5" x 23.50
	4-8 Layers	16.00" x 22.00"	16.00" x 22.00"
IPC Class	1-10 Layers	Class II	Class II
Isolation Ring Width	1-10 Layers	8 mil/side	6 mil/side
Surface Finish	All Layers	Lead Free HASL & HASL ENIG, Gold Fingers	Immersion Silver and Nickel, OSP, Wire Bond Gold, Others
Copper Weight	Outer Layers	1-2 oz.	3-10 oz.
	Inner Layers	1-2 oz.	3-6 oz.
Trace/Space Width	Outer/Inner Layers	.005" ± 10%	.004" ± 10%
Hole Location TDL	4-12 Layers	.015" ± 0.003"	.012" ± 0.003"
Dia. Drilled Holes		.010"	.006"
Plated Slots	All Layers	>0.031"	.025"
Smallest Plated - Through (Hole Finished)	.031" Thick Layers	.014" ± 0.003"	.010" ± 0.003"
	.062" Thick Layers	.014" ± 0.003"	.010" ± 0.003"
	>/.125" Thick Layers	.020" ± 0.003"	.016" ± 0.003"
Max. Aspect Ratio	1-10 Layers	10:1	12:1
Surface Mount Land Pitch		.050" ~ .025"	.020" - .012"
Soldermask (LPI)	Min. Solder Dam	.005" /Side	.003" /Side
Soldermask Color		Green	White, Red, Blue, Black, Clear, Gray, others available
Legend Color		White	Yellow, Black, Red, Blue, Gray, others available
Warp & Twist		1.5% ~ 05%	As Needed
Minimum Route Width		.062"	.031"
Impedance Control		± .10%	
Heat Shock		288°C ±5°%	
SMT Centerline Pitch for ET		Minimum .012"	
E-Test Voltage		50 ~ 250V, IPC-D-356, Net List Extraction/Compare	
File Format	Circuit	Gerber, 274-D or X	DXF, HPGL
	Drill	Excellon, Gerber	DXF, HPGL



Quality on time — all the time!

Phone: 800 364-4844 www.eiconnect.com Fax: 847 364-4892

